

Bill of Materials

TI DESIGNS

TIDA-00384 DLP Board (2513848)

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	2	C1,C2	9pF	CAP CER 9PF 50V NP0 0402	TDK	CGJ282C0G1H09000508A			402
2	3	C3,C4,C7	10uF	CAP CER 10UF 10V 20% X5R 0603	TDK	C1608X5R1A106M080AC			603
3	3	C5,C9,C10	0.22uF	CAP CER 0.22UF 25V 10% X5R 0402	TDK	C1005X5R1E224K050BC			402
4	1	C6	22uF	CAP CER 22UF 10V 20% X5R 0603	TDK	C1608X5R1A226M080AC			603
5	5	C8,C24,C39,C52,C53	1uF	CAP CER 1.0UF 10V X5R 0402	TDK	C1005X5R1A105M			402
6	28	C11,C18,C19,C20,C23,C25,C26,C27,C28,C29,C30,C31,C32,C33,C34,C35,C36,C37,C38,C40,C41,C42,C43,C44,C45,C46,C47,C48	0.1uF	CAP CER .1UF 16V X7R 0402	TDK	C1005X7R1C104K050BC	0402_AVXA		
7	4	C12,C13,C15,C54	22uF	CAP CER 22UF 6.3V 20% X5R 0603	TDK	C1608X5R0J226M			603
8	1	C14	2.2uF	CAP CER 2.2UF 6.3V X5R 0402	TDK	C1005X5R0J225M			402
9	1	C16	1uF	CAP CER 1.0UF 16V X5R 0402	TDK	C1005X5R1C105K			402
10	1	C17	4.7uF	CAP CER 4.7UF 6.3V 20% X5R 0402	TDK	C1005X5R0J475M			402
11	2	C21,C22	0.01uF	CAP CER 10000PF 16V X7R 10% 0402	TDK	C1005X7R1C103K			402
12	3	C49,C50,C51	0.1uF	CAP CER .10UF 25V X5R 0402	Taiyo Yuden	TMK105B1104KV-F			402
13	1	D1		SCHOTTKY RECT 40V 0.2A SOD882	NXP Semiconductors	PMEG4002EL315	SOD882		
14	2	F1,F2		FERRITE CHIP 80 OHM 1500MA 0402	Murata	BLM15PD800SN1D	BLM15P		
15	1	J1		CONN SOCKET F4S .4MM 50POS SMD	Panasonic	AXT550124	Panasonic_AXT550124_counter_clkwise_pinout		
16	1	J2		CONN HEADER EH SIDE 4POS 2.5MM	JST	S4B-EH(LF)(SN)	JST_S4B-EH		
17	3	J3,J4,J5		CONN HEADER 2H TOP 3POS 1.5MM	JST	B3B-ZR-SM4-TF(LF)(SN)(P)	JST_B3B-ZR-SM4-TF_LF_SN_P		
18	1	J6		CONN RCPT HI-SPD .5MM 60POS DL (stacking ht)	Samtec	QSH-030-01-L-D-A	Samtec_QSH-030-xx-x-D-A		
19	1	L1	10uH	INDUCTOR 10UH 20% 0805 SMD	Taiyo Yuden	CBL2012T100M			805
20	1	L2	2.2uH	INDUCTOR SHIELD PWR/ 2.2UH SMD Irms-4.76A	Cooper Bussmann	DR74-2R2-R	CooperBussmann_DR74		
21	1	L3	2.2uH	INDUCTOR 2.2UH 20% 1300MA 1008	Murata	LQM2HPN2R2MGOL	1008_2p5mmx2mm		
22	1	RT1	100k	THERMISTOR 100K OHM NTC 0402 SMD	Murata	NCP15WF104F03RC			402
23	1	R1	100	RES 100 OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF1000X			402
24	1	R2	953k	RES 953K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF9533X			402
25	2	R3,R4	43	RES 43 OHM 1/20W 5% 0201 SMD	Panasonic	ERJ-1GEJ430C			201
26	7	R5,R8,R9,R14,R25,R26,R30	100k	RES 100K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF1003X			402
27	8	R6,R7,R10,R11,R12,R13,R28,R29	30.1	RES 30.1 OHM 1/16W 1% 0402 SMD	Panasonic	ERJ-2RF30R1X			402
28	1	R15	0.039	RES 0.039 OHM 1/4W 1% 0603	Rohm	UCR03EWPPSR039			603
29	4	R16,R18,R23,R27	10k	RES 10K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF1002X			402
30	1	R17	300	RES 300 OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF3000X			402
31	3	R19,R20,R22	30.0k	RES 30.0K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF3002X			402
32	1	R21	0	RES 0.0 OHM 1/16W 0402 SMD	Panasonic	ERJ-2GEOR00X			402
33	1	R24	7.87k	RES 7.87K OHM 1/10W 1% 0402 SMD	Panasonic	ERJ-2RF7871X			402
34	3	TPGND1,TPGND2,TPGND4		TEST POINT PC MINI .040inD BLACK	Keystone		5001	KEYSTONE_TP_MINIATURE	
35	1	TPGND3		TEST POINT PC MINI .040inD BLACK	Keystone		5001	KEYSTONE_TP_MINIATURE	
36	1	U1		DLP3438	Texas Instruments	DLP3438ZEZ		DLP3438_13mmx13mm_VFBGA_201balls	
37	1	U2		DLPA2005	Texas Instruments	DLPA2005ERSLT		DLPA2005_RSL_S-PQFP-N48_QFN48	
38	1	U3		W25Q16DWSSIG	Winbond	W25Q16DWSSIG		SOIC-8_208mil	
39	1	X1		24MHz	KDS	1ZCCA24000EE0C		NDK_EX500A-CS05733	

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